ABSTRACT

A semiconductor device which does not require solder resist to be applied to the surface. Leads 54 are formed on one surface of a polyimide film 10, external connection terminals 11 are formed on the leads 54 to project from the other surface of the polyimide film 10 through via holes 30, and an IC chip 15 is adhered to the first surface, so that the leads 54 are covered by the IC chip 15, and the application of a solder resist can be omitted.

This Sheet Has Been Replaced

